

# **Memory Subsystems for IoT**

### Jackson Huang VP of Product and Ecosystem Marketing Spansion

August 7, 2014



Flash Memory Summit 2014 Santa Clara, CA

### **Explosion of More Intelligent** and Connected Devices

**Flash**Memory



## Interconnected Systems in the Connected World

**Flash** Memory

SUMMIT





## Powerful Nodes → Faster Controller → Faster Flash





## Spansion HyperBus<sup>™</sup> Interface and HyperFlash<sup>™</sup> Memory

### Spansion<sup>®</sup> HyperBus<sup>™</sup> Interface

- 12 pin interface
- Dramatically improves read performance while reducing pincount and board space
- Reuse of existing SPI pins
- Applicable to flash, RAM and peripheral devices

### **Compelling Features:**

- 5x the Read Speed of Quad SPI
  - 333MB/sec VCC = 1.8V
  - 200MB/sec VCC = 3.0V
- 96ns Initial Read Access Time
- 128, 256, 512 Mb densities

#### **Automotive Temperature**

- Supports Extended Temp Range
  - -40°C to 125°C

### Space-Saving 8x6mm BGA

- Common 24-ball BGA footprint
- SPI, QSPI, Dual QSPI or HyperFlash Memory



 Read Data Strobe (RDS) for accurate read data capture by host

